JG® Techology

PRODUCT DATA SHEET

To learn more about JGSEMI, please visit our website at
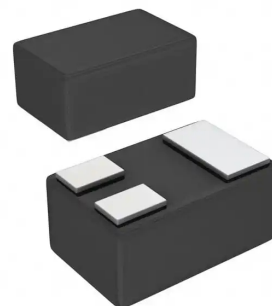
Datasheet   **Resources**   **Samples**

Features

- Operated at Low Logic Level Gate Drive
- N-Channel Switch with Low $R_{DS(on)}$
- Epoxy Meets UL 94 V-0 Flammability Rating
- ESD Human Body Model 2000V
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
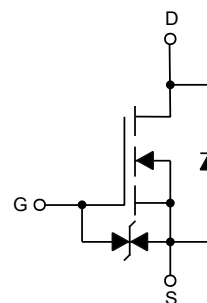- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

DFN1006-3

Maximum Ratings

- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Maximum Thermal Resistance: 138°C/W Junction to Ambient

Parameter	Symbol	Rating	Unit
Drain -source Voltage	V_{DS}	20V	V
Gate -Source Voltage	V_{GS}	±12	V
Drain Current-Continuous(Note 2)	I_D	0.75	A
Pulsed Drain Current	I_{DM}	2.8	A
Power Dissipation	P_D	0.9	W

Note: 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Curve Characteristics
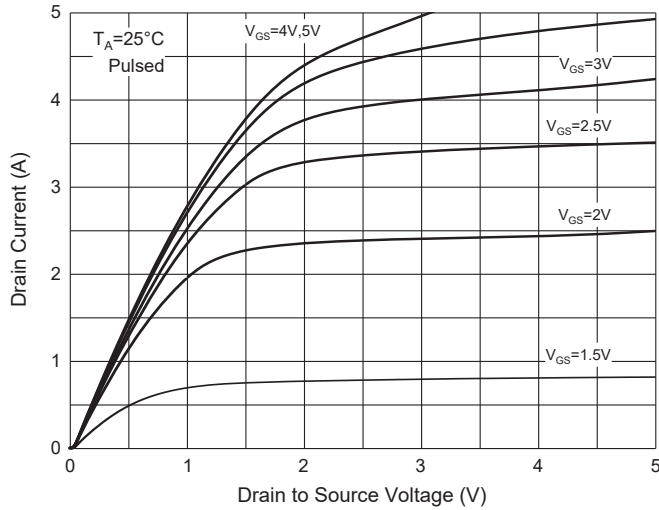
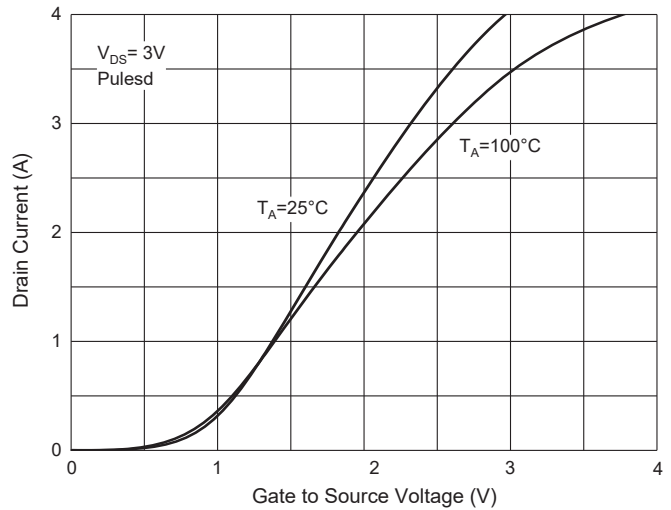Fig. 1 - Output Characteristics

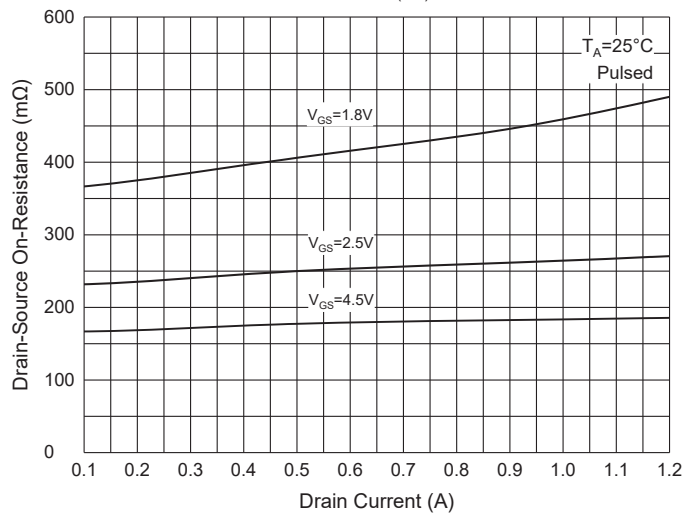Fig. 2 - Transfer Characteristics

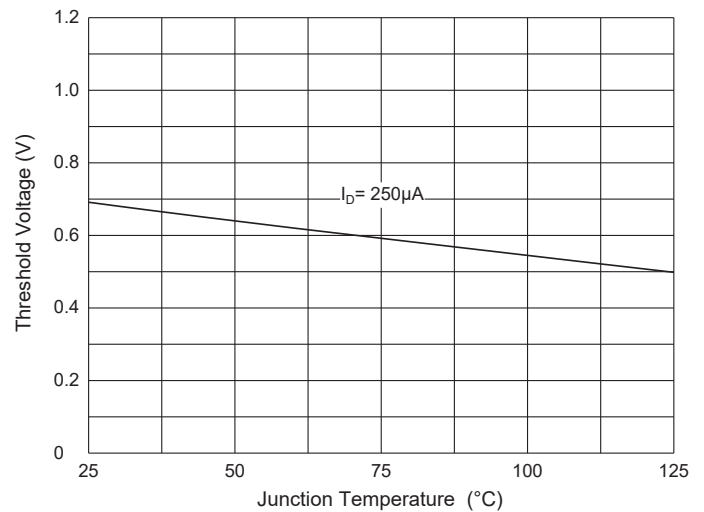

Fig. 3 - $R_{DS(ON)}$—I_D
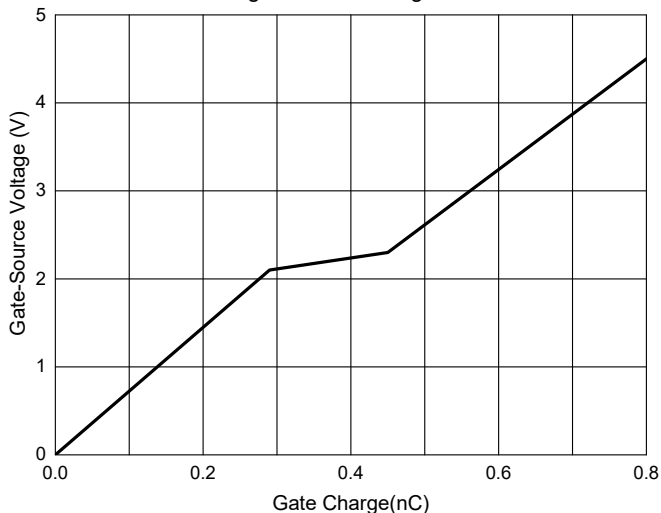

Fig. 4 - Threshold Voltage

Fig. 5 - Gate Charge
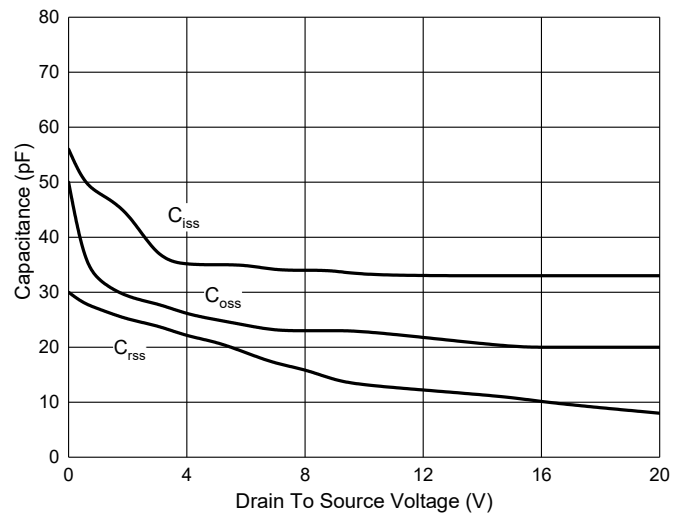

Fig. 6 - Capacitance Characteristics

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DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.018	0.022	0.45	0.55	
A1	0.000	0.002	0.00	0.05	
b	0.018	0.022	0.45	0.55	
b1	0.004	0.008	0.10	0.20	
c	0.005	0.007	0.12	0.18	
D	0.037	0.042	0.95	1.075	
E	0.022	0.026	0.55	0.675	
E1	0.006	0.010	0.15	0.25	
e	0.026		0.65		TYP.
L	0.008	0.012	0.20	0.30	
L1	0.0002		0.05		TYP.

Suggested Solder Pad Layout

(mm)

0.50

0.50

0.25

0.65

0.25

0.20

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